

MSKSEMI 美森科

SEMICONDUCTOR



ESD



TVS



TSS



MOV



GDT



PLED

MBRS360T3G(MS)

Product specification


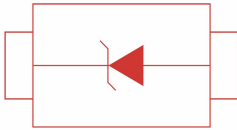

Features

- Small Compact Surface Mountable Package
- Highly Stable Oxide Passivated Junction
- Excellent Ability to Withstand Reverse Avalanche Energy Transients
- Guardring for Stress Protection
- Pb / RoHS Free

Mechanical Data

- Case : SMC Molded plastic
- Epoxy : UL94V-O rate flame retardant
- Lead : Lead Formed for Surface Mount
- Polarity : Color band denotes cathode end
- Mounting position : Any
- Weight : 0.21 gram

Reference News

Outline	Pin Configuration	Marking
		
SMC		

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Rating at 25 °C ambient temperature unless otherwise specified. Single phase, half wave, 60 Hz, resistive or inductive load. For capacitive load, derate current by 20%.

RATING	SYMBOL	VALUE	UNIT
Maximum Repetitive Reverse Voltage	V_{RRM}	60	V
Maximum Working Peak Reverse Voltage	V_{RWM}	60	V
Maximum DC Blocking Voltage	V_{DC}	60	V
Maximum Average Rectified Forward Current @ $T_L = 137\text{ °C}$	$I_{F(AV)}$	3.0	A
Maximum Non-repetitive Peak Surge Current (Surge applied at rated load conditions half wave, single phase ,60 Hz)	I_{FSM}	125	A
Maximum Instantaneous Forward Voltage (Note 1) ($I_F = 3.0\text{ A}$, $T_J = 25\text{ °C}$)	V_F	0.74	V
Maximum Instantaneous Reverse Current (Note1) ($V_R = V_{RRM}$, $T_J = 25\text{ °C}$) ($V_R = V_{RRM}$, $T_J = 100\text{ °C}$)	I_R	0.15	mA
	$I_{R(H)}$	10.0	
Thermal Resistance Junction to Ambient (Note 2)	$R_{\theta JA}$	164	°C/W
Thermal Resistance Junction to Lead (Note 2)	$R_{\theta JL}$	11	°C/W
Operating Junction and Storage Temperature Range	T_J, T_{STG}	- 65 to +175	°C

Notes :

- (1) Pulse Test : Pulse Width = 300 μ s Duty Cycle \leq 2%
- (2) Mounted with minimum recommended pad size, PC Board FR4

RATING AND CHARACTERISTIC CURVES

FIG.1 - CURRENT DERATING

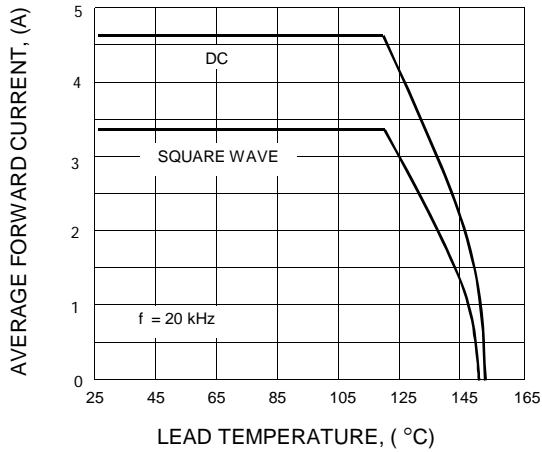


FIG.2 - FORWARD POWER DISSIPATION

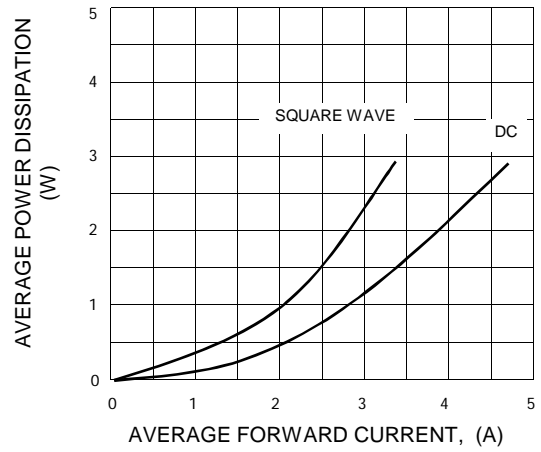


FIG.3 - TYPICAL FORWARD VOLTAGE

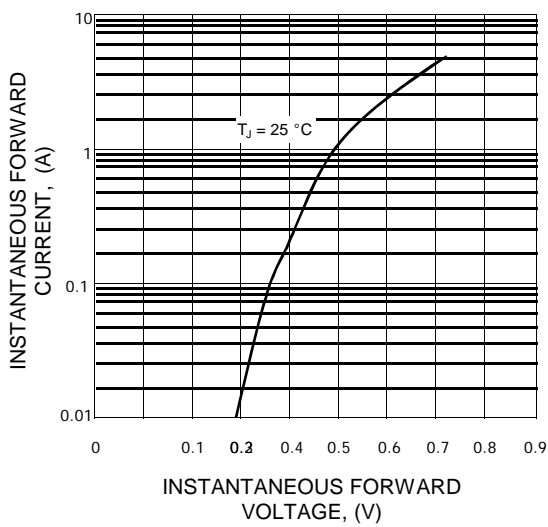
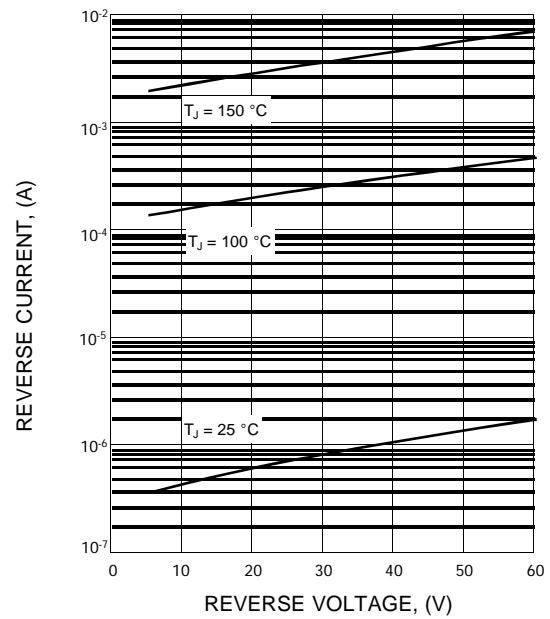
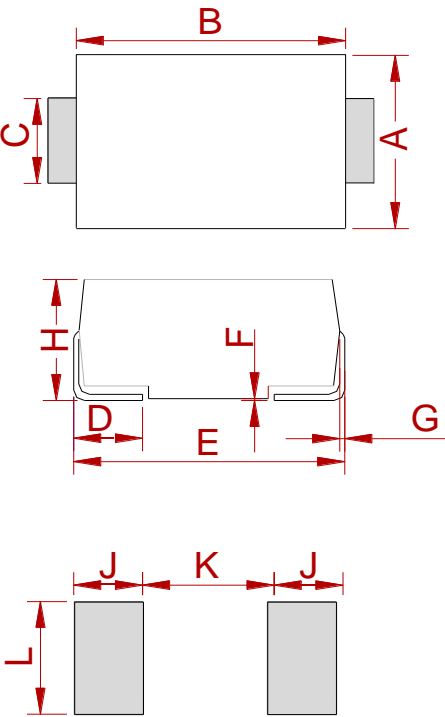


FIG.4 - TYPICAL REVERSE CURRENT



PACKAGE MECHANICAL DATA



DO-214AB (SMC)

Ref.	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	5.75	6.25	0.226	0.246
B	6.90	7.40	0.272	0.291
C	2.75	3.25	0.108	0.128
D	0.95	1.52	0.037	0.060
E	7.70	8.20	0.303	0.323
F	0.051	0.203	0.002	0.008
G	0.15	0.31	0.006	0.012
H	2.15	2.62	0.085	0.103
J	2.40		0.094	
K		4.20		0.165
L	3.30		0.130	

REEL SPECIFICATION

P/N	PKG	QTY
MBRS360T3G(MS)	SMC	3000

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